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# USB-grænseflader for data og energi – Del 1-3: Fælles komponenter – Specifikation for USB-type-CTM-kabel og -konnektor

Universal serial bus interfaces for data and  
power – Part 1-3: Common components – USB Type-  
CTM Cable and Connector Specification

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Edition 3.0 2018-05

# INTERNATIONAL STANDARD



**Universal serial bus interfaces for data and power –  
Part 1-3: Common components – USB Type-C™ Cable and Connector  
Specification**



## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### UNIVERSAL SERIAL BUS INTERFACES FOR DATA AND POWER –

#### Part 1-3: Common components – USB Type-C™ Cable and Connector Specification

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This third edition cancels and replaces the second edition published in 2017 and constitutes a technical revision.

The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this International Standard is based on the following documents:

CDV	Report on voting
100/3011/CDV	100/3099/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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This standard is the USB-IF publication USB Type-C™ Cable and Connector Specification Revision 1.3 as of July 14, 2017.

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# **Universal Serial Bus Type-C Cable and Connector Specification**

**Release 1.3  
July 14, 2017**

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## CONTENTS

FOREWORD.....	2
INTRODUCTION.....	4
1 Introduction .....	20
1.1 Purpose .....	20
1.2 Scope .....	20
1.3 Related Documents.....	21
1.4 Conventions.....	21
1.4.1 Precedence .....	21
1.4.2 Keywords .....	21
1.4.3 Numbering.....	22
1.5 Terms and Abbreviations .....	22
2 Overview .....	25
2.1 Introduction.....	25
2.2 USB Type-C Receptacles, Plugs and Cables .....	26
2.3 Configuration Process.....	28
2.3.1 Source-to-Sink Attach/Detach Detection .....	28
2.3.2 Plug Orientation/Cable Twist Detection.....	28
2.3.3 Initial Power (Source-to-Sink) Detection and Establishing the Data (Host-to-Device) Relationship.....	29
2.3.4 USB Type-C VBUS Current Detection and Usage .....	30
2.3.5 USB PD Communication .....	30
2.3.6 Functional Extensions.....	30
2.4 VBUS .....	31
2.5 VCONN.....	31
2.6 Hubs .....	32
3 Mechanical .....	32
3.1 Overview .....	32
3.1.1 Compliant Connectors .....	32
3.1.2 Compliant Cable Assemblies .....	32
3.1.3 Compliant USB Type-C to Legacy Cable Assemblies.....	32
3.1.4 Compliant USB Type-C to Legacy Adapter Assemblies.....	33
3.2 USB Type-C Connector Mating Interfaces.....	34
3.2.1 Interface Definition .....	34
3.2.2 Reference Designs .....	56
3.2.3 Pin Assignments and Descriptions.....	64
3.3 Cable Construction and Wire Assignments.....	65
3.3.1 Cable Construction (Informative) .....	65
3.3.2 Wire Assignments.....	67
3.3.3 Wire Gauges and Cable Diameters (Informative) .....	68
3.4 Standard USB Type-C Cable Assemblies.....	70
3.4.1 USB Full-Featured Type-C Cable Assembly.....	70
3.4.2 USB 2.0 Type-C Cable Assembly .....	71
3.4.3 USB Type-C Captive Cable Assemblies.....	72

3.5	Legacy Cable Assemblies .....	72
3.5.1	USB Type-C to <i>USB 3.1</i> Standard-A Cable Assembly .....	73
3.5.2	USB Type-C to <i>USB 2.0</i> Standard-A Cable Assembly .....	75
3.5.3	USB Type-C to <i>USB 3.1</i> Standard-B Cable Assembly .....	76
3.5.4	USB Type-C to <i>USB 2.0</i> Standard-B Cable Assembly .....	78
3.5.5	USB Type-C to <i>USB 2.0</i> Mini-B Cable Assembly .....	79
3.5.6	USB Type-C to <i>USB 3.1</i> Micro-B Cable Assembly .....	80
3.5.7	USB Type-C to <i>USB 2.0</i> Micro-B Cable Assembly .....	82
3.6	Legacy Adapter Assemblies .....	83
3.6.1	USB Type-C to <i>USB 3.1</i> Standard-A Receptacle Adapter Assembly .....	83
3.6.2	USB Type-C to <i>USB 2.0</i> Micro-B Receptacle Adapter Assembly .....	85
3.7	Electrical Characteristics .....	86
3.7.1	Raw Cable (Informative) .....	86
3.7.2	USB Type-C to Type-C Passive Cable Assemblies (Normative) .....	87
3.7.3	Mated Connector (Informative) .....	101
3.7.4	USB Type-C to Legacy Cable Assemblies (Normative) .....	105
3.7.5	USB Type-C to USB Legacy Adapter Assemblies (Normative) .....	109
3.7.6	Shielding Effectiveness Requirements (Normative) .....	112
3.7.7	DC Electrical Requirements (Normative) .....	114
3.8	Mechanical and Environmental Requirements (Normative) .....	117
3.8.1	Mechanical Requirements .....	117
3.8.2	Environmental Requirements .....	123
3.9	Docking Applications (Informative) .....	125
3.10	Implementation Notes and Design Guides .....	126
3.10.1	EMC Management (Informative) .....	126
3.10.2	Stacked and Side-by-Side Connector Physical Spacing (Informative) .....	128
3.10.3	Cable Mating Considerations (Informative) .....	129
4	Functional .....	130
4.1	Signal Summary .....	130
4.2	Signal Pin Descriptions .....	131
4.2.1	SuperSpeed USB Pins .....	131
4.2.2	USB 2.0 Pins .....	131
4.2.3	Auxiliary Signal Pins .....	131
4.2.4	Power and Ground Pins .....	131
4.2.5	Configuration Pins .....	131
4.3	Sideband Use (SBU) .....	132
4.4	Power and Ground .....	132
4.4.1	IR Drop .....	132
4.4.2	VBUS .....	133
4.4.3	VCONN .....	134
4.5	Configuration Channel (CC) .....	138
4.5.1	Architectural Overview .....	138
4.5.2	CC Functional and Behavioral Requirements .....	153
4.5.3	USB Port Interoperability Behavior .....	182
4.6	Power .....	195

4.6.1	Power Requirements during USB Suspend .....	196
4.6.2	VBUS Power Provided Over a USB Type-C Cable.....	197
4.7	USB Hubs .....	201
4.8	Power Sourcing and Charging.....	201
4.8.1	DFP as a Power Source.....	202
4.8.2	Non-USB Charging Methods .....	205
4.8.3	Sinking Host .....	205
4.8.4	Sourcing Device .....	205
4.8.5	Charging a System with a Dead Battery.....	205
4.8.6	USB Type-C Multi-Port Chargers .....	205
4.9	Electronically Marked Cables .....	208
4.9.1	Parameter Values .....	209
4.9.2	Active Cables .....	209
4.10	VCONN-Powered Accessories (VPAs) and VCONN-Powered USB Devices (VPDs) .....	209
4.10.1	VCONN-Powered Accessories (VPAs).....	210
4.10.2	VCONN-Powered USB Devices (VPDs) .....	210
4.11	Parameter Values .....	210
4.11.1	Termination Parameters .....	210
4.11.2	Timing Parameters .....	213
4.11.3	Voltage Parameters .....	216
5	Functional Extensions .....	217
5.1	Alternate Modes.....	217
5.1.1	Alternate Mode Architecture .....	217
5.1.2	Alternate Mode Requirements.....	218
5.1.3	Parameter Values .....	222
5.1.4	Example Alternate Mode – USB DisplayPort™ Dock.....	223
5.2	Managed Active Cables .....	225
5.2.1	Requirements for Managed Active Cables that respond to SOP' and SOP" .....	225
5.2.2	Cable Message Structure .....	226
5.2.3	Modal Cable Management .....	226
A	Audio Adapter Accessory Mode .....	228
A.1.	Overview .....	228
A.2.	Detail .....	228
A.3.	Electrical Requirements .....	230
A.4.	Example Implementations .....	231
A.4.1.	Passive 3.5 mm to USB Type-C Adapter – Single Pole Detection Switch .....	231
A.4.2.	3.5 mm to USB Type-C Adapter Supporting 500 mA Charge-Through.....	231
B	Debug Accessory Mode .....	233
B.1.	Overview .....	233
B.2.	Functional.....	233
B.2.1.	Signal Summary .....	235
B.2.2.	Port Interoperability .....	235
B.2.3.	Debug Accessory Mode Entry .....	235
B.2.4.	Connection State Diagrams .....	236
B.2.5.	DTS Port Interoperability Behavior.....	246

B.2.6.	Orientation Detection .....	257
B.3.	Security/Privacy Requirements: .....	257
C	USB Type-C Digital Audio.....	258
C.1.	Overview .....	258
C.2.	USB Type-C Digital Audio Specifications .....	258

## FIGURES

Figure 2-1	USB Type-C Receptacle Interface (Front View).....	26
Figure 2-2	USB Full-Featured Type-C Plug Interface (Front View) .....	26
Figure 3-1	USB Type-C Receptacle Interface Dimensions.....	37
Figure 3-2	Reference Design USB Type-C Plug External EMC Spring Contact Zones .....	40
Figure 3-3	USB Full-Featured Type-C Plug Interface Dimensions .....	41
Figure 3-4	Reference Footprint for a USB Type-C Vertical Mount Receptacle (Informative) .	44
Figure 3-5	Reference Footprint for a USB Type-C Dual-Row SMT Right Angle Receptacle (Informative) .....	45
Figure 3-6	Reference Footprint for a USB Type-C Hybrid Right-Angle Receptacle (Informative) .....	46
Figure 3-7	Reference Footprint for a USB Type-C Mid-Mount Dual-Row SMT Receptacle (Informative) .....	47
Figure 3-8	Reference Footprint for a USB Type-C Mid-Mount Hybrid Receptacle (Informative) .....	48
Figure 3-9	Reference Footprint for a USB 2.0 Type-C Through Hole Right Angle Receptacle (Informative).....	49
Figure 3-10	Reference Footprint for a USB 2.0 Type-C Single Row Right Angle Receptacle (Informative).....	50
Figure 3-11	USB 2.0 Type-C Plug Interface Dimensions .....	52
Figure 3-12	USB Type-C Plug EMC Shielding Spring Tip Requirements .....	55
Figure 3-13	Reference Design of Receptacle Mid-Plate .....	56
Figure 3-14	Reference Design of the Retention Latch .....	57
Figure 3-15	Illustration of the Latch Soldered to the Paddle Card Ground .....	57
Figure 3-16	Reference Design of the USB Full-Featured Type-C Plug Internal EMC Spring .	58
Figure 3-17	Reference Design of the USB 2.0 Type-C Plug Internal EMC Spring .....	59
Figure 3-18	Reference Design of Internal EMC Pad .....	61
Figure 3-19	Reference Design of a USB Type-C Receptacle with External EMC Springs .....	62
Figure 3-20	Reference Design for a USB Full-Featured Type-C Plug Paddle Card .....	63
Figure 3-21	Illustration of a USB Full-Featured Type-C Cable Cross Section, a Coaxial Wire Example with VCONN.....	66
Figure 3-22	Illustration of a USB Full-Featured Type-C Cable Cross Section, a Coaxial Wire Example without VCONN .....	66
Figure 3-23	USB Full-Featured Type-C Standard Cable Assembly .....	70
Figure 3-24	USB Type-C to USB 3.1 Standard-A Cable Assembly .....	73
Figure 3-25	USB Type-C to USB 2.0 Standard-A Cable Assembly .....	75

Figure 3-26	USB Type-C to <i>USB 3.1</i> Standard-B Cable Assembly .....	76
Figure 3-27	USB Type-C to <i>USB 2.0</i> Standard-B Cable Assembly .....	78
Figure 3-28	USB Type-C to <i>USB 2.0</i> Mini-B Cable Assembly .....	79
Figure 3-29	USB Type-C to <i>USB 3.1</i> Micro-B Cable Assembly .....	80
Figure 3-30	USB Type-C to <i>USB 2.0</i> Micro-B Cable Assembly .....	82
Figure 3-31	USB Type-C to <i>USB 3.1</i> Standard-A Receptacle Adapter Assembly .....	83
Figure 3-32	USB Type-C to <i>USB 2.0</i> Micro-B Receptacle Adapter Assembly.....	85
Figure 3-33	Illustration of Test Points for a Mated Cable Assembly.....	87
Figure 3-34	Recommended Differential Insertion Loss Requirement .....	88
Figure 3-35	Recommended Differential Return Loss Requirement .....	88
Figure 3-36	Recommended Differential Crosstalk Requirement.....	89
Figure 3-37	Recommended Differential Near-End and Far-End Crosstalk Requirement between USB D+/D- Pair and USB SuperSpeed Pair.....	89
Figure 3-38	Illustration of Insertion Loss Fit at Nyquist Frequency .....	90
Figure 3-39	Input Pulse Spectrum.....	91
Figure 3-40	IMR Limit as Function of $IL_{fitatNq}$ .....	92
Figure 3-41	IRL Limit as Function of $IL_{fitatNq}$ .....	94
Figure 3-42	Differential-to-Common-Mode Conversion Requirement .....	95
Figure 3-43	Requirement for Differential Coupling between CC and D+/D- .....	96
Figure 3-44	Requirement for Single-Ended Coupling between CC and D- in USB 2.0 Type-C Cables.....	97
Figure 3-45	Requirement for Single-Ended Coupling between CC and D- in USB Full- Featured Type-C Cables.....	97
Figure 3-46	Requirement for Differential Coupling between VBUS and D+/D- .....	98
Figure 3-47	Requirement for Single-Ended Coupling between SBU_A and SBU_B .....	99
Figure 3-48	Requirement for Single-Ended Coupling between SBU_A/SBU_B and CC .....	99
Figure 3-49	Requirement for Coupling between SBU_A and differential D+/D-, and SBU_B and differential D+/D-.....	100
Figure 3-50	Illustration of USB Type-C Mated Connector .....	101
Figure 3-51	Recommended Impedance Limits of a USB Type-C Mated Connector .....	102
Figure 3-52	Recommended Ground Void Dimensions for USB Type-C Receptacle.....	103
Figure 3-53	Recommended Differential Near-End and Far-End Crosstalk Limits between D+/D- Pair and SuperSpeed Pairs.....	105
Figure 3-54	Recommended Limits for Differential-to-Common-Mode Conversion .....	105
Figure 3-55	IMR Limit as Function of $IL_{fitatNq}$ for USB Type-C to Legacy Cable Assembly	108
Figure 3-56	IRL Limit as Function of $IL_{fitatNq}$ for USB Type-C to Legacy Cable Assembly.	109
Figure 3-57	Cable Assembly Shielding Effectiveness Testing .....	112
Figure 3-58	Shielding Effectiveness Pass/Fail Criteria .....	113
Figure 3-59	LLCR Measurement Diagram .....	114
Figure 3-60	Temperature Measurement Point .....	116
Figure 3-61	Example Current Rating Test Fixture Trace Configuration.....	117

Figure 3-62	Example of 4-Axis Continuity Test Fixture .....	119
Figure 3-63	Example Wrenching Strength Test Fixture for Plugs without Overmold.....	121
Figure 3-64	Reference Wrenching Strength Continuity Test Fixture .....	122
Figure 3-65	Example of Wrenching Strength Test Mechanical Failure Point .....	123
Figure 3-66	Wrenching Strength Test with Cable in Fixture .....	123
Figure 3-67	USB Type-C Cable Receptacle Flange Example .....	126
Figure 3-68	EMC Guidelines for Side Latch and Mid-plate .....	127
Figure 3-69	EMC Finger Connections to Plug Shell.....	127
Figure 3-70	EMC Pad Connections to Receptacle Shell .....	128
Figure 3-71	Examples of Connector Apertures .....	128
Figure 3-72	Recommended Minimum Spacing between Connectors.....	129
Figure 3-73	Recommended Minimum Plug Overmold Clearance .....	129
Figure 3-74	Cable Plug Overmold and an Angled Surface.....	130
Figure 4-1	Cable IR Drop .....	132
Figure 4-2	Cable IR Drop for powered cables .....	133
Figure 4-3	Logical Model for Data Bus Routing across USB Type-C-based Ports.....	140
Figure 4-4	Logical Model for USB Type-C-based Ports for the Direct Connect Device.....	140
Figure 4-5	Pull-Up/Pull-Down CC Model .....	142
Figure 4-6	Current Source/Pull-Down CC Model .....	142
Figure 4-7	Source Functional Model for CC1 and CC2 .....	145
Figure 4-8	Source Functional Model Supporting USB PD PR_Swap.....	146
Figure 4-9	Sink Functional Model for CC1 and CC2 .....	147
Figure 4-10	Sink Functional Model Supporting USB PD PR_Swap and VCONN_Swap.....	148
Figure 4-11	DRP Functional Model for CC1 and CC2.....	149
Figure 4-12	Connection State Diagram: Source .....	154
Figure 4-13	Connection State Diagram: Sink.....	155
Figure 4-14	Connection State Diagram: Sink with Accessory Support .....	156
Figure 4-15	Connection State Diagram: DRP .....	157
Figure 4-16	Connection State Diagram: DRP with Accessory and Try.SRC Support.....	158
Figure 4-17	Connection State Diagram: DRP with Accessory and Try.SNK Support .....	159
Figure 4-18	Sink Power Sub-States .....	175
Figure 4-19	Passive Cable eMarker State Diagram .....	177
Figure 4-20	Active Cable eMarker State Diagram.....	177
Figure 4-21	Source to Sink Functional Model.....	182
Figure 4-22	Source to DRP Functional Model .....	183
Figure 4-23	DRP to Sink Functional Model.....	185
Figure 4-24	DRP to DRP Functional Model – CASE 1 .....	186
Figure 4-25	DRP to DRP Functional Model – CASE 2 & 3.....	187
Figure 4-26	Source to Source Functional Model.....	190
Figure 4-27	Sink to Sink Functional Model.....	190

Figure 4-28	DRP to VPD Model .....	191
Figure 4-29	Source to Legacy Device Port Functional Model .....	192
Figure 4-30	Legacy Host Port to Sink Functional Model .....	193
Figure 4-31	DRP to Legacy Device Port Functional Model .....	194
Figure 4-32	Legacy Host Port to DRP Functional Model.....	195
Figure 4-33	Sink Monitoring for Current in Pull-Up/Pull-Down CC Model.....	198
Figure 4-34	Sink Monitoring for Current in Current Source/Pull-Down CC Model.....	199
Figure 4-35	USB PD over CC Pins.....	200
Figure 4-36	USB PD BMC Signaling over CC.....	200
Figure 4-37	USB Type-C Cable’s Output as a Function of Load for Non-PD-based USB Type-C Charging .....	203
Figure 4-38	0 – 3 A USB PD-based Charger USB Type-C Cable’s Output as a Function of Load .....	204
Figure 4-39	3 – 5 A USB PD-based Charger USB Type-C Cable’s Output as a Function of Load .....	204
Figure 4-40	Electronically Marked Cable with VCONN connected through the cable .....	208
Figure 4-41	Electronically Marked Cable with SOP’ at both ends .....	209
Figure 4-42	DRP Timing .....	214
Figure 5-1	Pins Available for Reconfiguration over the Full-Featured Cable .....	219
Figure 5-2	Pins Available for Reconfiguration for Direct Connect Applications .....	219
Figure 5-3	Alternate Mode Implementation using a USB Type-C to USB Type-C Cable.....	220
Figure 5-4	Alternate Mode Implementation using a USB Type-C to Alternate Mode Cable or Device .....	221
Figure 5-5	USB DisplayPort Dock Example .....	223
Figure 5-6	Managed Active Cable .....	226
Figure A-1	Example Passive 3.5 mm to USB Type-C Adapter .....	231
Figure A-2	Example 3.5 mm to USB Type-C Adapter Supporting 500 mA Charge-Through .....	233
Figure B-1	USB Type-C Debug Accessory Layered Behavior .....	234
Figure B-2	DTS Plug Interface .....	235
Figure B-3	Connection State Diagram: DTS Source .....	237
Figure B-4	Connection State Diagram: DTS Sink .....	238
Figure B-5	Connection State Diagram: DTS DRP .....	239
Figure B-6	TS Sink Power Sub-States .....	244

TABLES

Table 2-1	Summary of power supply options .....	31
Table 3-1	USB Type-C Standard Cable Assemblies .....	32
Table 3-2	USB Type-C Legacy Cable Assemblies .....	33
Table 3-3	USB Type-C Legacy Adapter Assemblies .....	34
Table 3-4	USB Type-C Receptacle Interface Pin Assignments .....	64
Table 3-5	USB Type-C Receptacle Interface Pin Assignments for USB 2.0-only Support .....	65

Table 3-6 USB Type-C Standard Cable Wire Assignments .....	67
Table 3-7 USB Type-C Cable Wire Assignments for Legacy Cables/Adapters .....	68
Table 3-8 Reference Wire Gauges for standard USB Type-C Cable Assemblies .....	69
Table 3-9 Reference Wire Gauges for USB Type-C to Legacy Cable Assemblies .....	69
Table 3-10 USB Full-Featured Type-C Standard Cable Assembly Wiring .....	71
Table 3-11 <i>USB 2.0</i> Type-C Standard Cable Assembly Wiring .....	72
Table 3-12 USB Type-C to <i>USB 3.1</i> Standard-A Cable Assembly Wiring .....	74
Table 3-13 USB Type-C to <i>USB 2.0</i> Standard-A Cable Assembly Wiring .....	75
Table 3-14 USB Type-C to <i>USB 3.1</i> Standard-B Cable Assembly Wiring .....	77
Table 3-15 USB Type-C to <i>USB 2.0</i> Standard-B Cable Assembly Wiring .....	78
Table 3-16 USB Type-C to <i>USB 2.0</i> Mini-B Cable Assembly Wiring .....	79
Table 3-17 USB Type-C to <i>USB 3.1</i> Micro-B Cable Assembly Wiring .....	81
Table 3-18 USB Type-C to <i>USB 2.0</i> Micro-B Cable Assembly Wiring .....	82
Table 3-19 USB Type-C to <i>USB 3.1</i> Standard-A Receptacle Adapter Assembly Wiring .....	84
Table 3-20 USB Type-C to <i>USB 2.0</i> Micro-B Receptacle Adapter Assembly Wiring .....	85
Table 3-21 Differential Insertion Loss Examples for USB SuperSpeed with Twisted Pair Construction .....	86
Table 3-22 Differential Insertion Loss Examples for USB SuperSpeed with Coaxial Construction .....	87
Table 3-23 Electrical Requirements for CC and SBU wires .....	95
Table 3-24 Coupling Matrix for Low Speed Signals .....	96
Table 3-25 Maximum Mutual Inductance (M) between VBUS and Low Speed Signal Lines....	98
Table 3-26 USB D+/D– Signal Integrity Requirements for USB Type-C to USB Type-C Passive Cable Assemblies .....	100
Table 3-27 USB Type-C Mated Connector Recommended Signal Integrity Characteristics (Informative) .....	104
Table 3-28 USB D+/D– Signal Integrity Requirements for USB Type-C to Legacy USB Cable Assemblies .....	106
Table 3-29 Design Targets for USB Type-C to <i>USB 3.1</i> Gen 2 Legacy Cable Assemblies (Informative) .....	107
Table 3-30 USB Type-C to <i>USB 3.1</i> Gen 2 Legacy Cable Assembly Signal Integrity Requirements (Normative) .....	107
Table 3-31 USB D+/D– Signal Integrity Requirements for USB Type-C to Legacy USB Adapter Assemblies (Normative) .....	110
Table 3-32 Design Targets for USB Type-C to <i>USB 3.1</i> Standard-A Adapter Assemblies (Informative) .....	110
Table 3-33 USB Type-C to <i>USB 3.1</i> Standard-A Receptacle Adapter Assembly Signal Integrity Requirements (Normative) .....	111
Table 3-34 Current Rating Test PCB .....	116
Table 3-35 Force and Moment Requirements .....	120
Table 3-36 Environmental Test Conditions .....	124
Table 3-37 Reference Materials .....	125
Table 4-1 USB Type-C List of Signals .....	130

Table 4-2	VBUS Source Characteristics .....	133
Table 4-3	VBUS Sink Characteristics .....	134
Table 4-4	USB Type-C Source Port's VCONN Requirements Summary .....	135
Table 4-5	VCONN Source Characteristics.....	135
Table 4-6	Cable VCONN Sink Characteristics.....	136
Table 4-7	VCONN-Powered Accessory (VPA) Sink Characteristics .....	137
Table 4-8	VCONN-Powered USB Device (VPD) Sink Characteristics .....	138
Table 4-9	USB Type-C-based Port Interoperability.....	141
Table 4-10	Source Perspective .....	143
Table 4-11	Source (Host) and Sink (Device) Behaviors by State .....	144
Table 4-12	USB PD Swapping Port Behavior Summary.....	151
Table 4-13	Power Role Behavioral Model Summary.....	152
Table 4-14	Source Port CC Pin State.....	160
Table 4-15	Sink Port CC Pin State .....	160
Table 4-16	Mandatory and Optional States .....	180
Table 4-17	Precedence of power source usage.....	196
Table 4-18	USB Type-C Current Advertisement and PDP Labeling .....	198
Table 4-19	SOP' and SOP" Timing.....	209
Table 4-20	Source CC Termination (Rp) Requirements.....	211
Table 4-21	Sink CC Termination (Rd) Requirements.....	211
Table 4-22	Powered Cable Termination Requirements.....	211
Table 4-23	Sink CC Termination Requirements.....	212
Table 4-24	SBU Termination Requirements .....	212
Table 4-25	VBUS and VCONN Timing Parameters .....	213
Table 4-26	DRP Timing Parameters.....	214
Table 4-27	CC Timing.....	215
Table 4-28	CC Voltages on Source Side – Default USB .....	216
Table 4-29	CC Voltages on Source Side – 1.5 A @ 5 V .....	216
Table 4-30	CC Voltages on Source Side – 3.0 A @ 5 V .....	216
Table 4-31	Voltage on Sink CC Pins (Default USB Type-C Current only) .....	216
Table 4-32	Voltage on Sink CC pins (Multiple Source Current Advertisements).....	217
Table 5-1	USB Safe State Electrical Requirements .....	222
Table 5-2	USB Billboard Device Class Availability Following Alternate Mode Entry Failure .....	222
Table 5-3	Alternate Mode Signal Noise Ingression Requirements .....	222
Table A-1	USB Type-C Analog Audio Pin Assignments .....	229
Table A-2	USB Type-C Analog Audio Pin Electrical Parameter Ratings.....	230
Table B-1	DTS to TS Port Interoperability .....	235
Table B-2	Rp/Rp Charging Current Values for a DTS Source .....	244
Table B-3	Mandatory and Optional States.....	246

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### Revision History

Revision	Date	Description
1.0	August 11, 2014	Initial Release
1.1	April 3, 2015	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.
1.2	March 25, 2016	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.
1.3	July 14, 2017	Reprint release including incorporation of all approved ECNs as of the revision date plus editorial clean-up.

## 1 Introduction

With the continued success of the USB interface, there exists a need to adapt USB technology to serve newer computing platforms and devices as they trend toward smaller, thinner and lighter form-factors. Many of these newer platforms and devices are reaching a point where existing USB receptacles and plugs are inhibiting innovation, especially given the relatively large size and internal volume constraints of the Standard-A and Standard-B versions of USB connectors. Additionally, as platform usage models have evolved, usability and robustness requirements have advanced and the existing set of USB connectors were not originally designed for some of these newer requirements. This specification is to establish a new USB connector ecosystem that addresses the evolving needs of platforms and devices while retaining all of the functional benefits of USB that form the basis for this most popular of computing device interconnects.

### 1.1 Purpose

This specification defines the USB Type-C™ receptacles, plug and cables.

The USB Type-C Cable and Connector Specification is guided by the following principles:

- Enable new and exciting host and device form-factors where size, industrial design and style are important parameters
- Work seamlessly with existing USB host and device silicon solutions
- Enhance ease of use for connecting USB devices with a focus on minimizing user confusion for plug and cable orientation

The USB Type-C Cable and Connector Specification defines a new receptacle, plug, cable and detection mechanisms that are compatible with existing USB interface electrical and functional specifications. This specification covers the following aspects that are needed to produce and use this new USB cable/connector solution in newer platforms and devices, and that interoperate with existing platforms and devices:

- USB Type-C receptacles, including electro-mechanical definition and performance requirements
- USB Type-C plugs and cable assemblies, including electro-mechanical definition and performance requirements
- USB Type-C to legacy cable assemblies and adapters
- USB Type-C-based device detection and interface configuration, including support for legacy connections
- USB Power Delivery optimized for the USB Type-C connector

The USB Type-C Cable and Connector Specification defines a standardized mechanism that supports Alternate Modes, such as repurposing the connector for docking-specific applications.

### 1.2 Scope

This specification is intended as a supplement to the existing *USB 2.0*, *USB 3.1* and *USB Power Delivery* specifications. It addresses only the elements required to implement and support the USB Type-C receptacles, plugs and cables.

Normative information is provided to allow interoperability of components designed to this specification. Informative information, when provided, may illustrate possible design implementations.

### 1.3 Related Documents

- USB 2.0** *Universal Serial Bus Revision 2.0 Specification*  
This includes the entire document release package.  
<http://www.usb.org/developers/docs>
- USB 3.1** *Universal Serial Bus Revision 3.1 Specification*  
This includes the entire document release package.  
<http://www.usb.org/developers/docs>
- USB PD** *USB Power Delivery Specification, Revision 2.0, Version 1.3, January 12, 2017*  
*USB Power Delivery Specification, Revision 3.0, Version 1.1, January 12, 2017 (including errata and ECNs through June 12, 2017)*  
<http://www.usb.org/developers/docs>
- USB BB** *USB Billboard Device Class Specification, Revision 1.21, September 8, 2016*  
<http://www.usb.org/developers/docs>
- USB BC** *Battery Charging Specification, Revision 1.2 (including errata and ECNs through March 15, 2012), March 15, 2012*  
<http://www.usb.org/developers/docs>

### 1.4 Conventions

#### 1.4.1 Precedence

If there is a conflict between text, figures, and tables, the precedence shall be tables, figures, and then text.

#### 1.4.2 Keywords

The following keywords differentiate between the levels of requirements and options.

##### 1.4.2.1 Informative

Informative is a keyword that describes information with this specification that intends to discuss and clarify requirements and features as opposed to mandating them.

##### 1.4.2.2 May

May is a keyword that indicates a choice with no implied preference.

##### 1.4.2.3 N/A

N/A is a keyword that indicates that a field or value is not applicable and has no defined value and shall not be checked or used by the recipient.

##### 1.4.2.4 Normative

Normative is a keyword that describes features that are mandated by this specification.